

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Field device integration (FDI) –  
Part 1: Overview**

**Intégration des appareils de terrain (FDI) –  
Partie 1: Vue d'ensemble**



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International Standard IEC 62769-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) support for generic protocol extension for faster adoption of other technologies;
- b) digital signature now include trusted timestamping for long term validation of FDI Package;
- c) support of new protocols.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65E/758/FDIS	65E/768/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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## INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles – Generic Protocol Extensions
- Part 101-1: Profiles – Foundation Fieldbus H1
- Part 101-2: Profiles – Foundation Fieldbus HSE
- Part 103-1: Profiles – PROFIBUS
- Part 103-4: Profiles – PROFINET
- Part 109-1: Profiles – HART and WirelessHART
- Part 115-2: Profiles – Protocol-specific Definitions for Modbus RTU
- Part 150-1: Profiles – ISA 100.11a

## FIELD DEVICE INTEGRATION (FDI) –

### Part 1: Overview

#### 1 Scope

This part of IEC 62769 describes the concepts and overview of the Field Device Integration (FDI) specifications. The detailed motivation for the creation of this technology is also described (see 4.1). Reading this document is helpful to understand the other parts of this multi-part standard.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC TR 62541-1, *OPC Unified Architecture – Part 1: Overview and concepts*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*

#### 3 Terms, definitions, abbreviated terms and conventions

##### 3.1 Terms and definitions

For the purposes of this document, the following terms and definitions given in IEC TR 62541-1, IEC 62541-3, IEC 62541-4, IEC 62541-5, IEC 62541-100, as well as the following apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

##### 3.1.1 Field Device Integration FDI

device integration and device management technology, combining base concepts and technology aspects of the Electronic Device Description Language (EDDL) according to IEC 61804 and Field Device Tool (FDT®) according to IEC 62453, as well as in IEC 62541-1 (OPC UA)

Note 1 to entry: The combination of those different proven technologies ensures a secure life cycle and the ability to address all challenges of Device Integration and Device Management in a scalable manner.